


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13417	
1.3 Title of PCN	ULA resin- TPM VFQFPN32 – Package upgrade to support	
1.4 Product Category	ST33TPHF20, ST33TPHF2E, ST33TPHF2X	
1.5 Issue date	2022-05-05	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marie-France FLORENTIN
2.1.2 Marketing Manager	Denis FARISON
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	(Not Defined)	Amkor ATP3

4. Description of change

	Old	New
4.1 Description	This PCN replaces PCN 13025. Molding resin change for ST33TPHF20, ST33TPHF2E, ST33TPHF2X	Molding resin change for ST33TPHF20, ST33TPHF2E, ST33TPHF2X to Ultra Low Alpha molding resin to improve Soft Error Rate. The scope of the changes is no more limited to molding resin. The list of changes is updated in this PCN (see detailed description)
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	- Form: impact o Marking: second level interconnect modification (“e4” changed by “e3”) o surface finish: Matte Sn finishing instead of Nickel/Palladium/Gold - Fit: no impact (no change for external dimensions and tolerances) - Function: no impact (no change for electrical, environmental, mechanical, thermal performance characteristics)	

5. Reason / motivation for change

5.1 Motivation	The FIT (failure in time) related to alpha particle will be decreased by a factor 10 with the ULA resin.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	For each Commercial Product impacted by the change, a new Finished Good codification will be created. This Finished Good codification is present on the label. See detailed description
-----------------	---

7. Timing / schedule

7.1 Date of qualification results	2022-11-07
7.2 Intended start of delivery	2023-01-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	
-----------------	--

8.2 Qualification report and qualification results	In progress	Issue Date	
--	-------------	------------	--

9. Attachments (additional documentations)

13417 Public product.pdf 13417 PCN TPM VFQFPN32 - Package upgrade to support ULA resin v1.0.pdf
--

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ST33HTPH2X32AHD5	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved